



Statement of Materials, Construction

Revision: 1.0
Date: 23-Feb-05

LEAD-FREE -- 5L-T0263 -- TABLE OF MATERIAL DECLARATION								
No.	Component Name	Material Name	Component Weight (grams)	Materials Analysis (Element / Compound)	CAS Number	Material Mass (Gram)	Material Weight % (of Total Pkg)	Material Weight % (of Component)
1	Leadframe	Copper Alloy	0.85370	Cu	7440-50-8	0.83302	59.29393	97.578
				Fe	7439-89-6	0.01946	1.38546	2.28
				Pb	7439-92-1	0.00006	0.00425	0.007
				P	7723-14-0	0.00015	0.01094	0.018
				Zn	7440-66-6	0.00100	0.07110	0.117
2	Die	Silicon Chip	0.01450	Si	7440-21-3	0.01443	1.02694	99.5
3	Die attach material	Conductive Epoxy	0.00420	Epoxy resin (5-25)	Proprietary	0.00063	0.04484	15
				Silver (70-85)	7440-21-3	0.00336	0.23916	80
				Aromatic Amine (1-10)	Proprietary	0.00021	0.01495	5
4	Wire	Gold	0.00124	Au	7440-57-5	0.00124	0.08825	99.99
5	Lead Finish	Tin	0.009865	Sn	7440-31-5	0.00987	0.70218	100
6	Encapsulation	Epoxy Resin	0.5214	Fused Silica	7631-86-9	0.38531	27.42638	73.9
				Crystalline Silica	14808-60-7	0.02086	1.48451	4
				Phenol Resin	9003-35-4	0.05214	3.71128	10
				Epoxy resin	29690-82-2	0.05214	3.71128	10
				Carbon Black	1333-86-4	0.00521	0.37113	1
				Antimony trioxide	1309-64-4	0.00574	0.40824	1.1
Total Package weight			1.40491					

Note: Composition derived from MSDS and material C of C from Vendors;
 Component Weight based on assembly of generic parts.

Conclusion:

The analysis table above shows that this package meets the following RoHS requirements for EACH PACKAGE COMPONENT (mold compound, lead frame, etc.)

	Maximum Allowable Limit (ppm)	Maximum Allowable Limit (wt %)
Lead*	1000 ppm	0.10%
Mercury	1000 ppm	0.10%
Cadmium	100 ppm	0.01%
Hexavalent Chromium	1000 ppm	0.10%
Polybrominated Biphenyls (PBB)	1000 ppm	0.10%
Polybrominated Biphenylethers (PBDE)	1000 ppm	0.10%

* Lead is allowed up to 4% as an alloying agent in copper-based alloys